SCLS149C - DECEMBER 1982 - REVISED DECEMBER 2002

- Wide Operating Voltage Range of 2 V to 6 V
- High-Current 3-State Outputs Can Drive Up To 15 LSTTL Loads
- Low Power Consumption, 80-μA Max I<sub>CC</sub>
- Typical t<sub>pd</sub> = 8 ns
- ±6-mA Output Drive at 5 V
- Low Input Current of 1 μA Max
- Lock Bus-Latch Capability
- True Logic

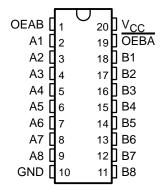
#### description/ordering information

These octal bus transceivers are designed for asynchronous two-way communication between data buses. The control-function implementation allows for maximum flexibility in timing.

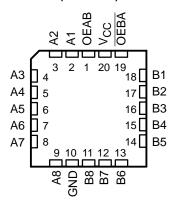
The 'HC623 devices allow data transmission from the A bus to the B bus or from the B bus to the A bus, depending upon the logic levels at the output-enable (OEAB and OEBA) inputs.

OEAB and OEBA disable the device so that the buses are effectively isolated. The dual-enable configuration gives the transceivers the capability to store data by simultaneously enabling OEAB and OEBA. Each output reinforces its input in this transceiver configuration. When both OEAB and OEBA are enabled and all other data sources to the two sets of bus lines are in the high-impedance state, both sets of bus lines (16 total) remain at their last states. The 8-bit codes appearing on the two sets of buses are identical.

#### SN54HC623 . . . J OR W PACKAGE SN74HC623 . . . DW, N, OR NS PACKAGE (TOP VIEW)



## SN54HC623 . . . FK PACKAGE (TOP VIEW)



#### ORDERING INFORMATION

TA	PACK	AGE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – N Tub		SN74HC623N	SN74HC623N
–40°C to 85°C	COIC DW	Tube	SN74HC623DW	LICCOS
	SOIC - DW	Tape and reel	SN74HC623DWR	HC623
	SOP - NS	Tape and reel	SN74HC623NSR	HC623
	CDIP – J	Tube	SNJ54HC623J	SNJ54HC623J
–55°C to 125°C	CFP – W	Tube	SNJ54HC623W	SNJ54HC623W
	LCCC - FK	Tube	SNJ54HC623FK	SNJ54HC623FK

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



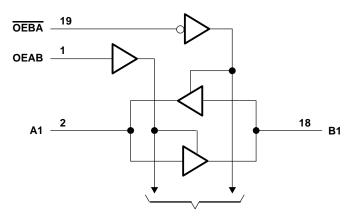
Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



#### **FUNCTION TABLE**

INP	UTS	OPERATION
OEBA	OEAB	OPERATION
L	L	B data to A bus
Н	Н	A data to B bus
Н	L	Isolation
L	Н	B data to A bus, A data to B bus

#### logic diagram (positive logic)



**To Seven Other Transceivers** 

### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>		0.5 V to 7	7 V
Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{CC}$ ) (see	ee Note 1)	±20 r	nΑ
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0 or V <sub>O</sub> > V <sub>CO</sub>	C) (see Note 1)	) ±20 r	nΑ
Continuous output current, $I_O(V_O = 0 \text{ to } V_{CC})$		±35 r	nΑ
Continuous current through V <sub>CC</sub> or GND		±70 r	nΑ
Package thermal impedance, θ <sub>JA</sub> (see Note 2)	: DW package	9	/W
	N package	69°C	/W
	NS package	60°C	/W
Storage temperature range, T <sub>stq</sub>		–65°C to 150	°С

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
  - 2. The package thermal impedance is calculated in accordance with JESD 51-7.



#### recommended operating conditions (see Note 3)

			SN	154HC62	23	SN	174HC62	23	LINUT
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage		2	5	6	2	5	6	V
		V <sub>CC</sub> = 2 V	1.5			1.5			
VIH	High-level input voltage	V <sub>CC</sub> = 4.5 V	3.15			3.15			V
		V <sub>CC</sub> = 6 V	4.2		ih	4.2			
		V <sub>CC</sub> = 2 V		Ą	0.5			0.5	
VIL	Low-level input voltage	V <sub>CC</sub> = 4.5 V		20	1.35			1.35	V
		VCC = 6 V		6	1.8			1.8	
VI	Input voltage		0 2	5	VCC	0		VCC	V
٧o	Output voltage		0		VCC	0		VCC	V
		V <sub>CC</sub> = 2 V	Q.		1000			1000	
Δt/Δν	Input transition rise/fall time	V <sub>CC</sub> = 4.5 V			500			500	ns
		VCC = 6 V		400				400	
TA	Operating free-air temperature		-55		125	-40		85	°C

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

		<b>TEST 66</b>	NO TIONS	.,	Т	A = 25°C	;	SN54H	IC623	SN74H	IC623	
PAR	AMETER	TEST CO	NDITIONS	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
				2 V	1.9	1.998		1.9		1.9		
VOH			$I_{OH} = -20  \mu A$	4.5 V	4.4	4.499		4.4		4.4		
		VI = VIH or VIL		6 V	5.9	5.999		5.9		5.9		V
			$I_{OH} = -6 \text{ mA}$	4.5 V	3.98	4.3		3.7		3.84		
			$I_{OH} = -7.8 \text{ mA}$	6 V	5.48	5.8		5.2	!h	5.34		
				2 V		0.002	0.1		0.1		0.1	
			$I_{OL} = 20 \mu A$	4.5 V		0.001	0.1	4	0.1		0.1	
VOL	$V_{OL}$ $V_{I} = V_{IH} \text{ or } V_{II}$			6 V		0.001	0.1	C)	0.1		0.1	V
			I <sub>OL</sub> = 6 mA	4.5 V		0.17	0.26	20	0.4		0.33	
	=		$I_{OL} = 7.8 \text{ mA}$	6 V		0.15	0.26	O <sub>V</sub>	0.4		0.33	
IJ	OEAB or OEBA	V <sub>I</sub> = V <sub>CC</sub> or 0		6 V		±0.1	±100	7	±1000		±1000	nA
loz	A or B	VO = VCC or 0		6 V		±0.01	±0.5		±10		±5	μΑ
Icc	_	$V_I = V_{CC}$ or 0,	I <sub>O</sub> = 0	6 V			8		160		80	μΑ
Ci	OEAB or OEBA			2 V to 6 V		3	10		10		10	pF

# switching characteristics over recommended operating free-air temperature range, $C_L = 50$ pF (unless otherwise noted) (see Figure 1)

	FROM	то		Τ <sub>Δ</sub>	\ = 25°C	;	SN54H	IC623	SN74H	C623			
PARAMETER	(INPUT)	(OUTPUT)	vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT		
			2 V		29	105		160		130			
t <sub>pd</sub>	A or B	B or A	4.5 V		10	21		32		26	ns		
·			6 V		8	18		27		22			
			2 V		112	210		315		265			
t <sub>en</sub>	OEBA	Α	4.5 V		27	42		63		53	ns		
			6 V		20	36		54		45			
			2 V		40	150		225		190			
<sup>t</sup> dis	OEBA	Α	4.5 V		18	30		45		38	ns		
			6 V		16	26	.<	38		32			
			2 V		112	210	Ź	315		265			
t <sub>en</sub>	OEAB	В	4.5 V		27	42	200	63		53	ns		
			6 V		20	36	Q.	54		45			
			2 V		40	150		225		190			
<sup>t</sup> dis	OEAB	В	4.5 V		18	30		45		38	ns		
			6 V		16	26		38		32			
			2 V		20	60		90		75			
t <sub>t</sub>			A or B	A or B	4.5 V		8	12		18		15	ns
			6 V		6	10		15		13			

# switching characteristics over recommended operating free-air temperature range, $C_L$ = 150 pF (unless otherwise noted) (see Figure 1)

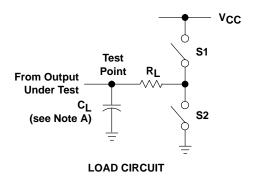
	FROM	то		T,	\ = 25°C	;	SN54H	C623	SN74H	IC623		
PARAMETER	(INPUT)	(OUTPUT)	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT	
			2 V		44	135		200		170		
<sup>t</sup> pd	A or B	B or A	4.5 V		14	27		40		34	ns	
•			6 V		11	23		34		29		
			2 V		130	270		405		335		
	OEBA	Α	4.5 V		31	54		81		67	ns	
			6 V	23 46 69						56		
t <sub>en</sub>			2 V		130	270	0,	405		335		
	OEAB	В	4.5 V		31	54	<sup>l</sup> Q <sub>C</sub>	81		67	ns	
			6 V		23	46	V <sub>Q</sub>	69		56		
			2 V		45	210		315		265		
t <sub>t</sub>		A or B	A or B	4.5 V		17	42		63		53	ns
			6 V		13	36		53		45		

## operating characteristics, $T_A = 25^{\circ}C$

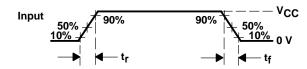
PARAMETER	TEST CONDITIONS	TYP	UNIT
C <sub>pd</sub> Power dissipation capacitance per transceiver	No load	40	pF



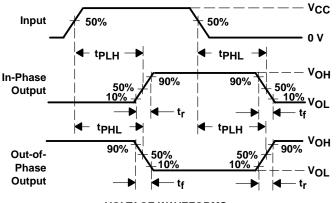
#### PARAMETER MEASUREMENT INFORMATION

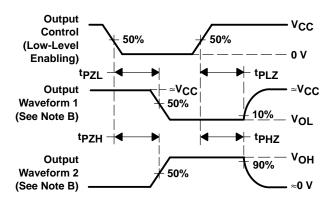


PARAI	METER	RL	CL	S1	S2
	tPZH		50 pF or	Open	Closed
<sup>t</sup> en	tPZL	<b>1 k</b> Ω	150 pF	Closed	Open
	tPHZ 1 kΩ		50 pF	Open	Closed
<sup>t</sup> dis	tPLZ	1 K22	50 pr	Closed	Open
t <sub>pd</sub> or	t <sub>pd</sub> or t <sub>t</sub>		50 pF or 150 pF	Open	Open



## VOLTAGE WAVEFORM INPUT RISE AND FALL TIMES





VOLTAGE WAVEFORMS
PROPAGATION DELAY AND OUTPUT TRANSITION TIMES

VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES FOR 3-STATE OUTPUTS

NOTES: A. C<sub>L</sub> includes probe and test-fixture capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz,  $Z_{O} = 50 \Omega$ ,  $t_{f} = 6 \text{ ns}$ .
- D. The outputs are measured one at a time with one input transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tplH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms



www.ti.com 2-Dec-2024

#### PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74HC623DW	ACTIVE	SOIC	DW	20	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC623	Samples
SN74HC623N	ACTIVE	PDIP	N	20	20	RoHS & Non-Green	NIPDAU	N / A for Pkg Type	-40 to 85	SN74HC623N	Samples
SN74HC623NSR	ACTIVE	SOP	NS	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC623	Samples

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

**Important Information and Disclaimer:** The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.



## **PACKAGE OPTION ADDENDUM**

www.ti.com 2-Dec-2024

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

## **PACKAGE MATERIALS INFORMATION**

www.ti.com 7-Dec-2024

#### TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HC623NSR	SOP	NS	20	2000	330.0	24.4	8.4	13.0	2.5	12.0	24.0	Q1

**PACKAGE MATERIALS INFORMATION** 

www.ti.com 7-Dec-2024



#### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74HC623NSR	SOP	NS	20	2000	367.0	367.0	45.0

## **PACKAGE MATERIALS INFORMATION**

www.ti.com 7-Dec-2024

#### **TUBE**



#### \*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN74HC623DW	DW	SOIC	20	25	507	12.83	5080	6.6
SN74HC623N	N	PDIP	20	20	506	13.97	11230	4.32

## N (R-PDIP-T\*\*)

### PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.





SOIC



#### NOTES:

- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

  2. This drawing is subject to change without notice.

  3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
- 5. Reference JEDEC registration MS-013.



SOIC



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOIC



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



#### **MECHANICAL DATA**

### NS (R-PDSO-G\*\*)

## 14-PINS SHOWN

#### PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



#### IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATA SHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

TI objects to and rejects any additional or different terms you may have proposed.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2024, Texas Instruments Incorporated